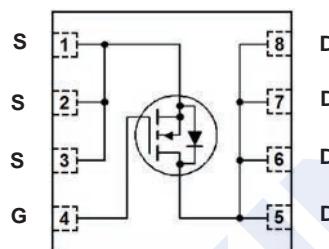


N-Channel MOSFET

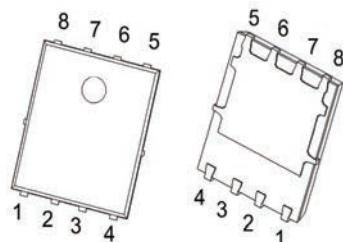
2KK5125DFN

■ Features

- V_{DS} (V) = 60 V
- I_D = 80 A
- $R_{DS(ON)}$ (at V_{GS} = 10 V) < 6 mΩ
- $R_{DS(ON)}$ (at V_{GS} = 4.5 V) < 11 mΩ



PDFN5x6-8

■ Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ^A	I_D	80	A
$T_C = 100^\circ\text{C}$		50	
Pulsed Drain Current ^B	I_{DM}	300	
Single Pulse Avalanche Energy ^C	E_{AS}	500	mJ
Power Dissipation ^D	P_D	120	W
Thermal Resistance, Junction- to-Ambient ^E	$R_{\theta JA}$	20	°C/W
Thermal Resistance, Junction- to-Case	$R_{\theta JC}$	1.04	
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{stg}	-55 to 150	

Notes:

- A. The maximum current rating is package limited.
- B. Repetitive rating; pulse width limited by max. junction temperature.
- C. $V_{DD}=50$ V, $R_G=25$ Ω, $L=0.5\text{mH}$, starting $T_J=25$ °C.
- D. P_D is based on max. junction temperature, using junction-case thermal resistance.
- E. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_a=25$ °C.

N-Channel MOSFET**2KK5125DFN****■ Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = 250 \mu\text{A}, V_{GS} = 0\text{V}$	60			V
Zero Gate Voltage Drain Current	$I_{DS(on)}$	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
Gate to Source Leakage Current	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
On Characteristics						
Gate to Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.5	2	2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$			6	$\text{m}\Omega$
		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$			11	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 100 \text{ KHz}$		4950		pF
Output Capacitance	C_{oss}			950		
Reverse Transfer Capacitance	C_{rss}			65		
Switching Characteristics						
Total Gate Charge	Q_g	$V_{GS} = 10 \text{ V}, V_{DS} = 50 \text{ V}, I_D = 50 \text{ A}$		83		nC
Gate Source Charge	Q_{gs}			11		
Gate Drain Charge	Q_{gd}			9		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10 \text{ V}, V_{DD} = 30 \text{ V}, I_D = 25 \text{ A}, R_{GEN} = 2 \Omega$		22.5		ns
Turn-On Rise Time	t_r			6.7		
Turn-Off Delay Time	$t_{d(off)}$			80.3		
Turn-Off Fall Time	t_f			26.9		
Drain-Source Diode Characteristics						
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 25 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		68		ns
Body Diode Reverse Recovery Charge	Q_{rr}			73		
Maximum Body-Diode Continuous Current	I_S	$V_G = V_D = 0 \text{ V}$, Force Current			80	A
Diode Forward Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_S = 20 \text{ A}$			1.2	V

■ Marking

Marking	K5125 KC***
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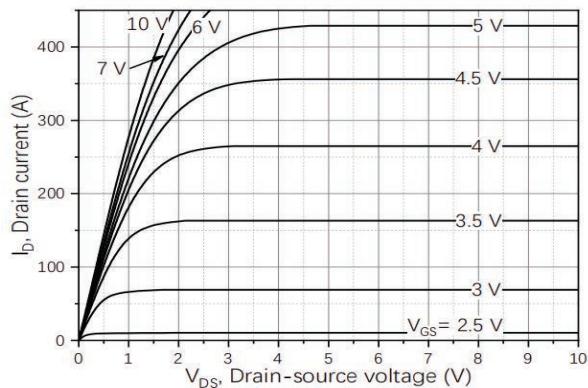
N-Channel MOSFET**2KK5125DFN****■ Typical Characteristics**

Figure1. Output Characteristics

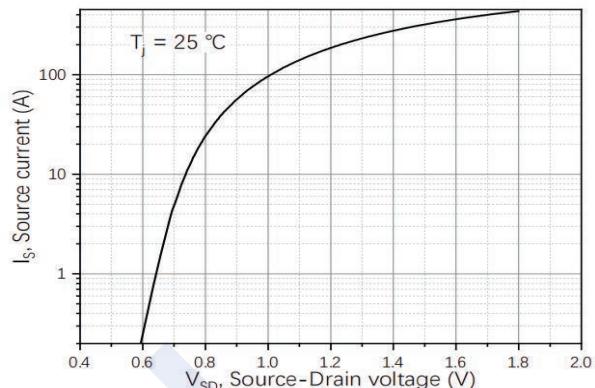


Figure2. Transfer Characteristics

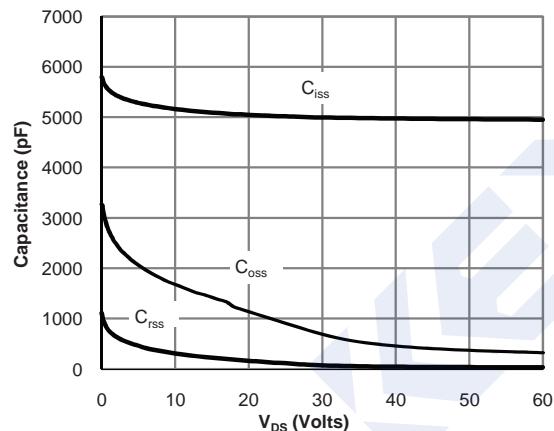


Figure3. Capacitance Characteristics

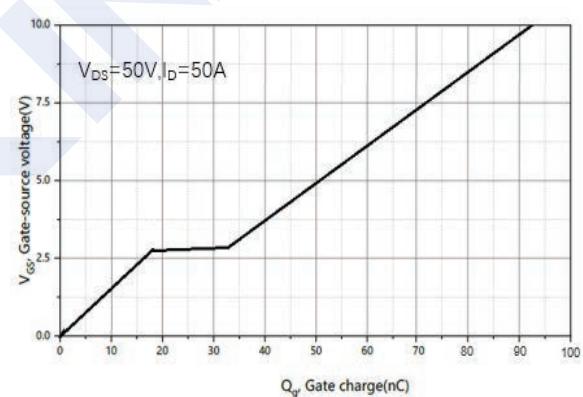


Figure4. Gate Charge

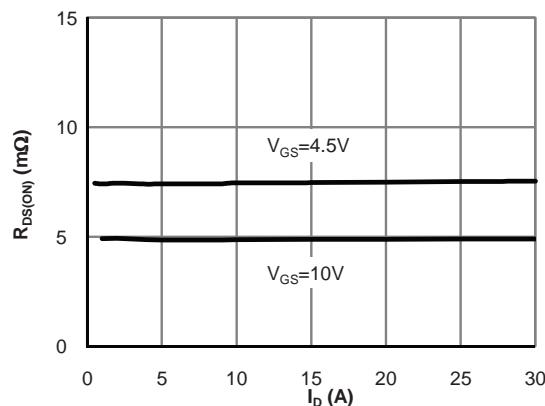


Figure5. Drain-Source on Resistance

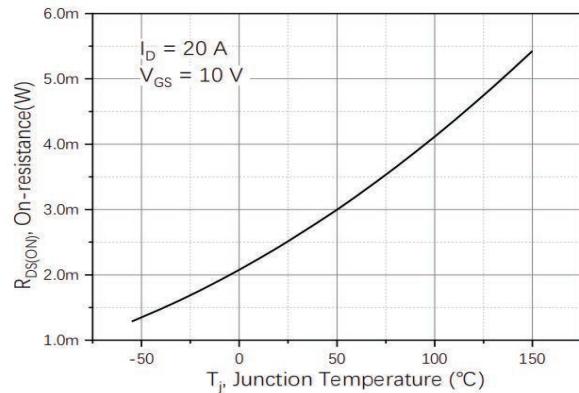


Figure6. Drain-Source on Resistance

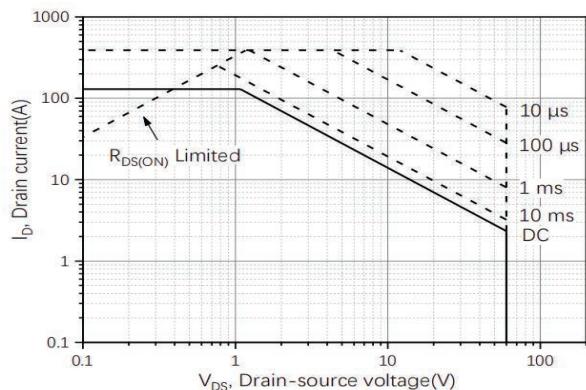
N-Channel MOSFET**2KK5125DFN**

Figure7. Safe Operation Area

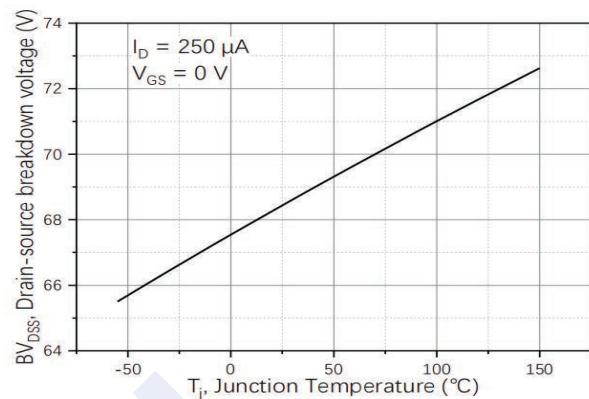
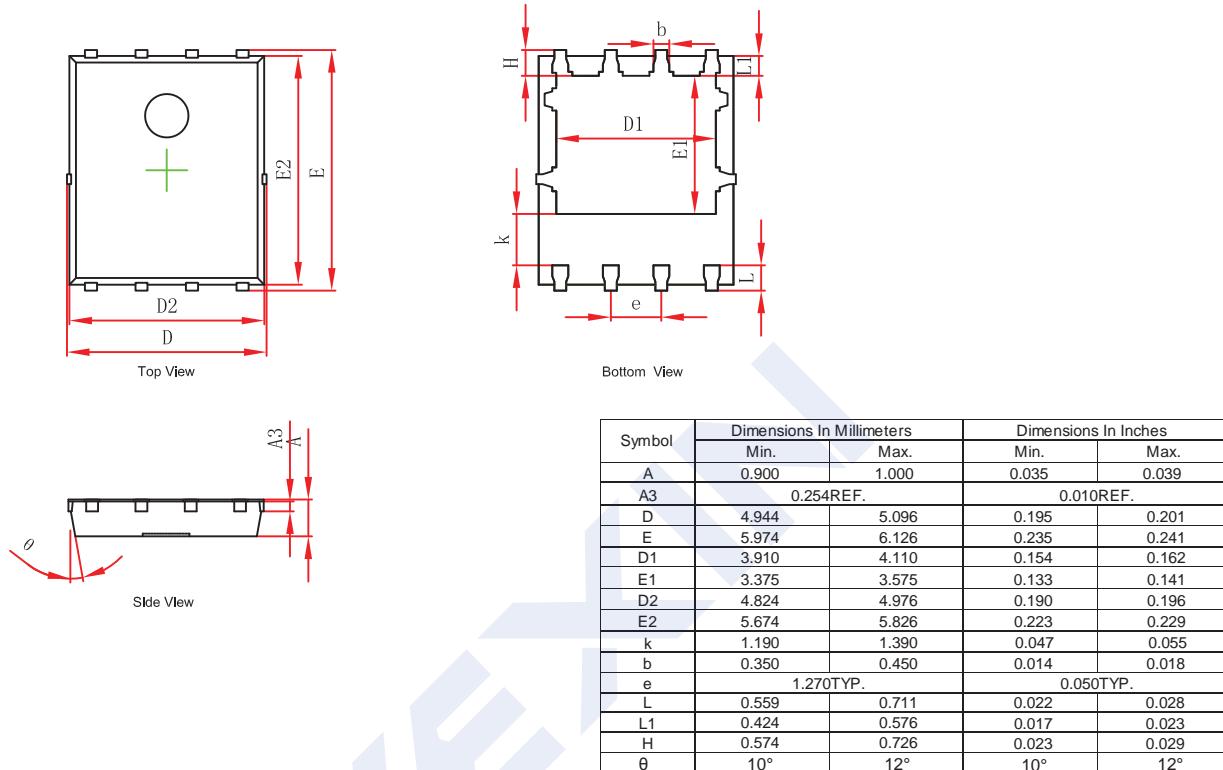
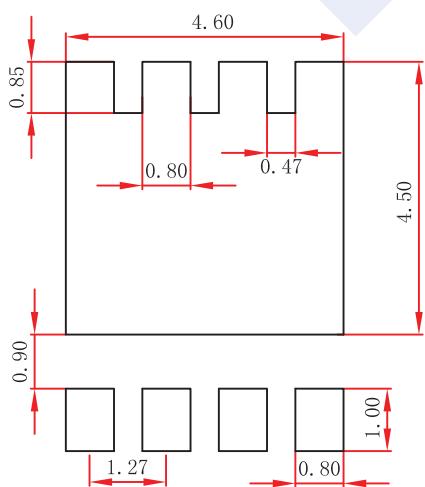


Figure8. Drain-source breakdown voltage

N-Channel MOSFET**2KK5125DFN****■ PDFN5x6-8 Package Outline Dimensions****■ PDFN5x6-8 Suggested Pad Layout****Note:**

1. Controlling dimension:in millimeters.
- 2.General tolerance: $\pm 0.05\text{mm}$.
- 3.The pad layout is for reference purposes only.